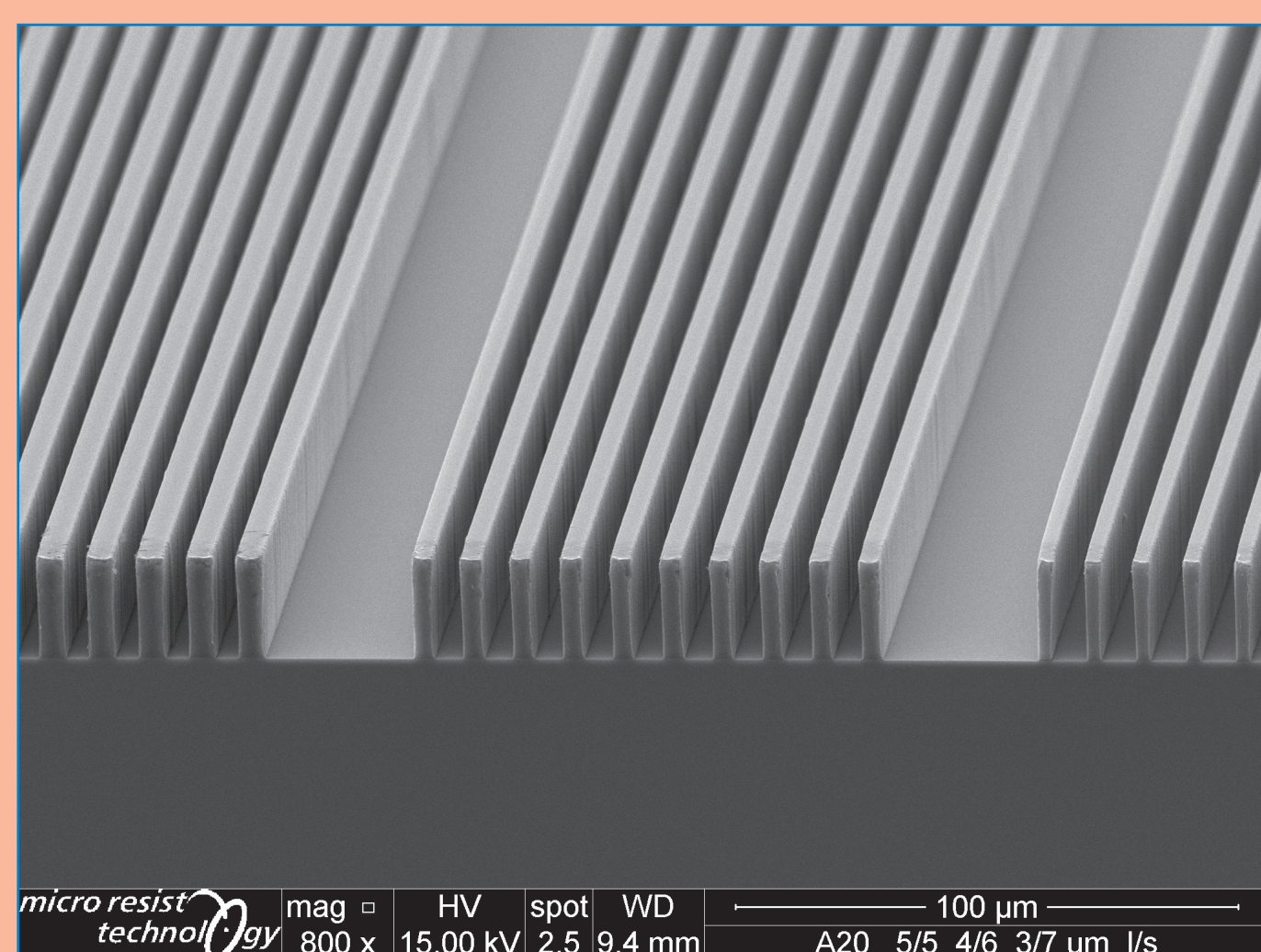
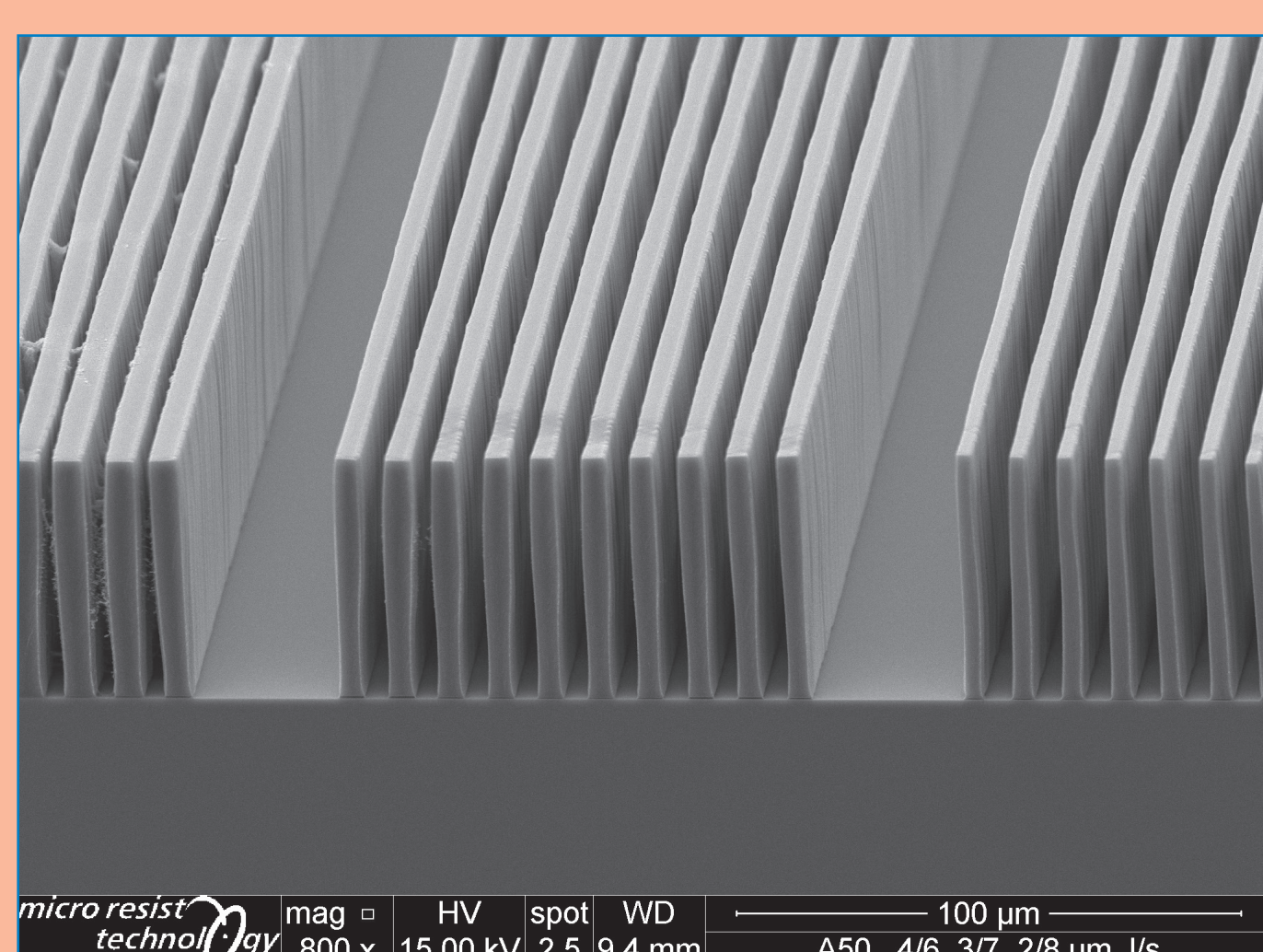


Dry Film Photoresists

Dry film Resists for MEMS, Microfluidics and Packaging applications



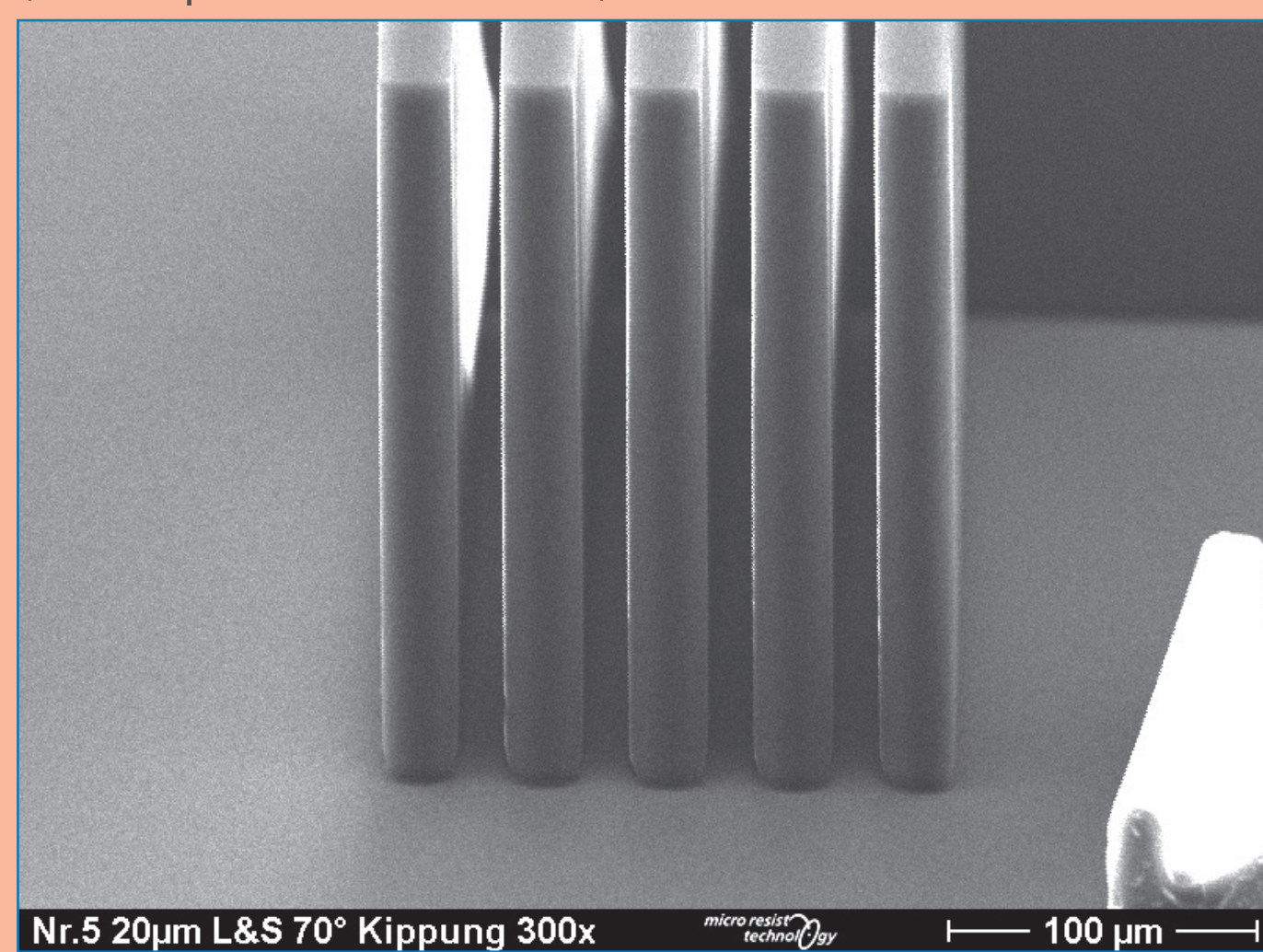
3 µm L/S in 20 µm ADEX™ film



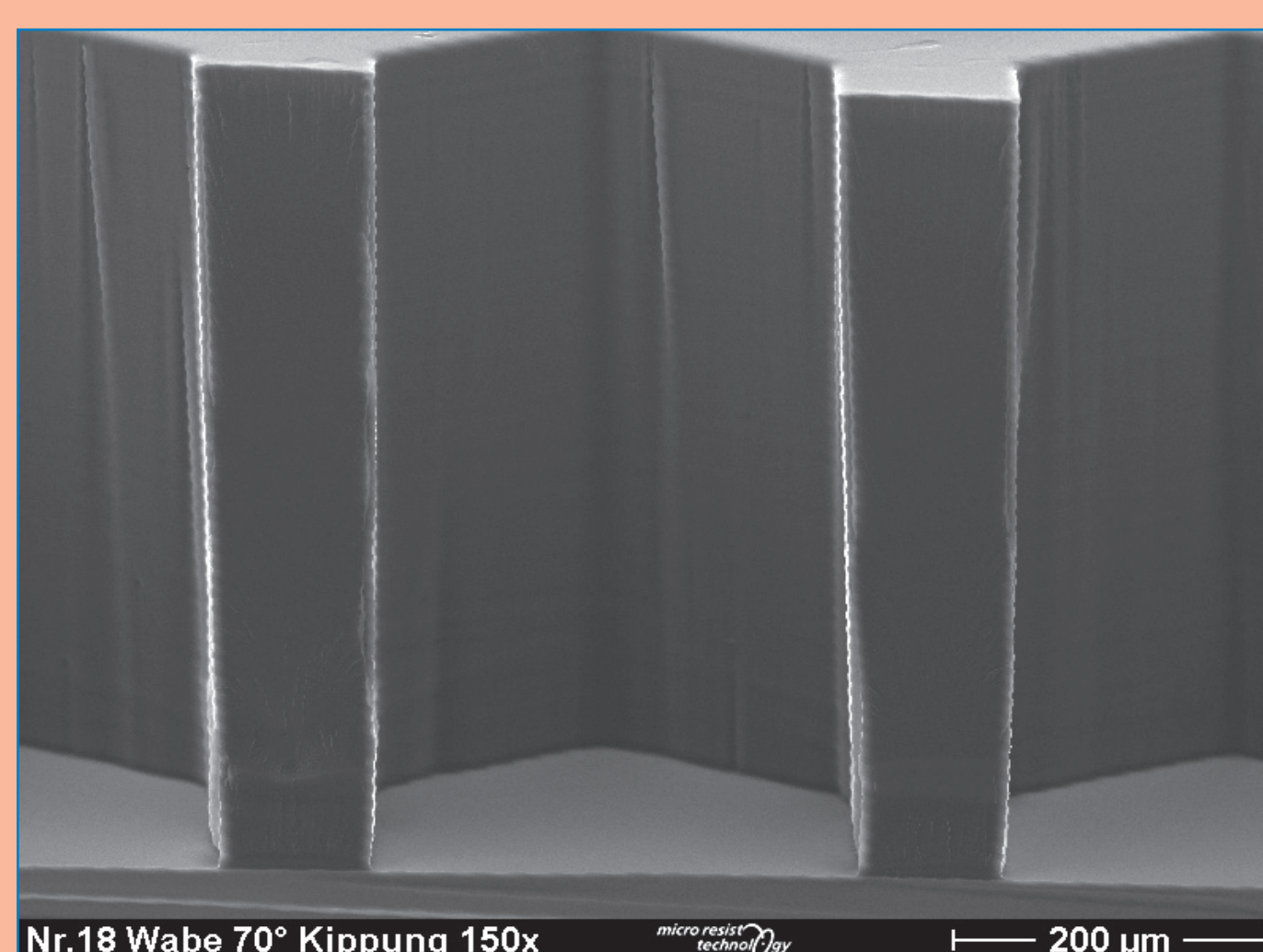
5 µm L/S in 50 µm ADEX™ film



L/S Features in 140 µm ADEX™ film (multiple lamination)



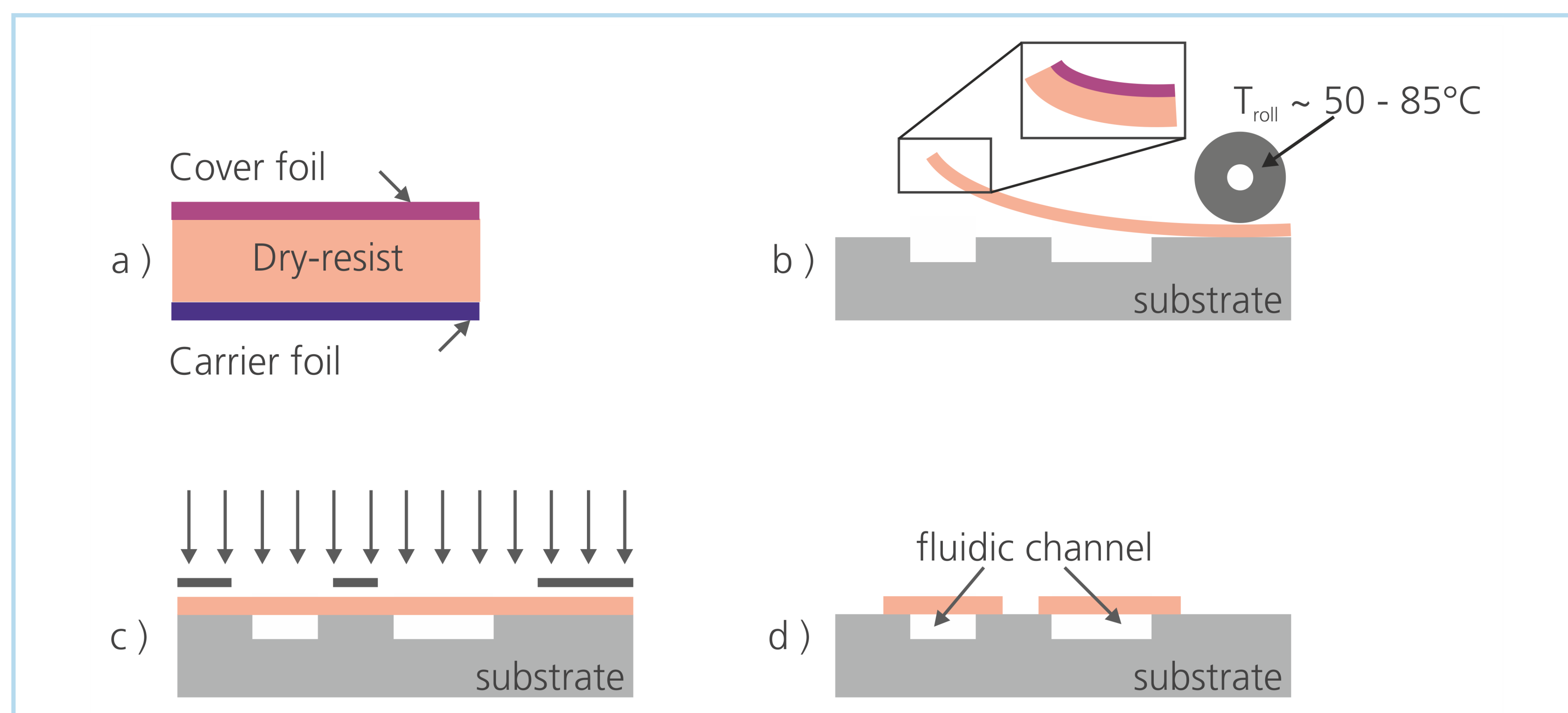
L/S features in 250 µm SUEX™ film



Features in 500 µm SUEX™ film

ADEX™ and SUEX™ (DJ MICROLAMINATES Inc.) **Dry Film Photoresists** are high performance, *i-line sensitive*, photo-imageable epoxy films available as both *sheets and rolls*. These films are easily applied using low cost laminating equipment, eliminating the waste and inconvenience associated with spin coating. Film thicknesses from **5 µm to 500 µm** and aspect ratios > 20:1 are possible with these convenient to use sheets. Sheets are pre-cut to variety of standard substrate and panel sizes and rolls are available in a variety of widths and lengths. A solvent-free manufacturing technique yields exceptional film thickness uniformity and extremely low average surface roughness.

Typical Process:



Remove PET cover foil ⇒ Laminate using vacuum or hot roll laminator ⇒ Soft Bake: 85 – 95 °C ⇒ Remove PET foil ⇒ Expose: *i-line* ⇒ Develop: mr-Dev 600, immersion ⇒ Hard Bake (optional): 125 – 200 °C

Items in this series:

Resist	Film thickness Sheet/ roll sizes*	Developer
ADEX™ A	5 µm; 10 µm; 20 µm; 50 µm <i>Pre-cut sheets</i> (wafer cut sizes, round/ square/ rectangular) and rolls	mr-Dev CH
SUEX™ K	20 µm; 25 µm; 30 µm; 40 µm; 50 µm; 75 µm; 100 µm; 125 µm; 150 µm; 200 µm; 225 µm; 250 µm; 300 µm; 350 µm; 400 µm; 500 µm <i>Pre-cut sheets</i> (wafer cut sizes, round/ square/ rectangular)	mr-Dev 600

* Other sheets sizes and rolls on request

Applications:

- Plating moulds
- Microfluidics
- Wafer Level Packaging
- Polymer MEMS
- Spacers

micro resist technology GmbH is a distributor of DJ Microlaminates Dry Film Photoresists for MEMS, microfluidics and packaging applications.

